



## Final Product Change Notification

202012016F01 : MPC7448 and MPC7447A epoxy underfill raw material change to new supplier

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** May 12, 2021 **Effective date:** Aug 10, 2021

### Management summary

MPC7448 and MPC7447A Henkel FP4502 epoxy underfill raw material change to new supplier.

### Change Category

- |  |   |  |  |   |
|--|---|--|--|---|
| <input type="checkbox"/> Wafer<br>Fab<br>Process   | <input type="checkbox"/> Assembly<br>Process              | <input type="checkbox"/> Product Marking             | <input type="checkbox"/> Test<br>Process   | <input type="checkbox"/> Design                               |
| <input type="checkbox"/> Wafer<br>Fab<br>Materials | <input checked="" type="checkbox"/> Assembly<br>Materials | <input type="checkbox"/> Mechanical<br>Specification | <input type="checkbox"/> Test<br>Equipment | <input type="checkbox"/> Errata                               |
| <input type="checkbox"/> Wafer<br>Fab<br>Location  | <input type="checkbox"/> Assembly<br>Location             | <input type="checkbox"/> Packing/Shipping/Labeling   | <input type="checkbox"/> Test<br>Location  | <input type="checkbox"/> Electrical<br>spec./Test<br>coverage |
| <input type="checkbox"/> Firmware                  | <input type="checkbox"/> Other                            |  |  |   |

## PCN Overview

### Description

NXP is pleased to announce the qualification of MPC7448 and MPC7447A epoxy underfill raw material from Resin A (supplier 1) to Resin B (supplier 2) to ensure supply continuity. Material property of Resin B is equivalent to Resin A. Hence the epoxy performance of Resin B is comparable to Resin A.

### Reason

Resin A (supplier 1) was discontinued by the vendor. Resin B (supplier 2) was selected as the replacement and has comparable material properties to Resin A. There is no change to the underfill manufacturing process besides this material change.

#### **Identification of Affected Products**

Product identification does not change

### **Product Availability**

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#### **Sample Information**

Samples are available upon request

#### **Production**

Planned first shipment

### **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality

#### **Data Sheet Revision**

No impact to existing datasheet

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

### **Additional information**

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Self qualification: [view online](#)

### **Timing and Logistics**

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 11, 2021.

### **Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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